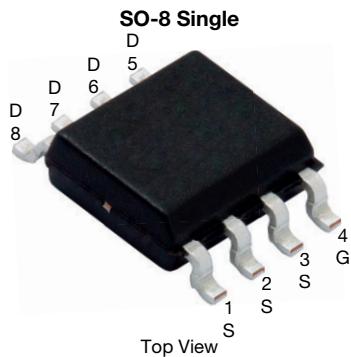


## P-Channel 30 V (D-S) MOSFET



Top View

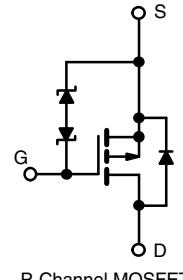
### FEATURES

- Extended  $V_{GS}$  range ( $\pm 25$  V) for adaptor switch applications
- Extremely low  $R_{DS(on)}$
- TrenchFET® power MOSFET
- 100 %  $R_g$  and UIS tested
- Typical ESD performance: 4000 V (HBM)
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT  
HALOGEN  
FREE

### APPLICATIONS

- Adaptor switch, load switch
- Power management
- Notebook computers and portable battery packs



P-Channel MOSFET

### PRODUCT SUMMARY

|   |        |
|---|--------|
| $V_{DS}$ (V)  | -30    |
| $R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -10$ V  | 0.0065 |
| $R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -6$ V   | 0.0082 |
| $R_{DS(on)}$ max. ( $\Omega$ ) at $V_{GS} = -4.5$ V | 0.0112 |
| $Q_g$ typ. (nC)                                     | 66     |
| $I_D$ (A) <sup>a</sup>                              | -29    |
| Configuration                                       | Single |

### ORDERING INFORMATION

|                                 |                  |
|---------------------------------|------------------|
| Package                         | SO-8             |
| Lead (Pb)-free and halogen-free | Si4491EDY-T1-GE3 |

### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25$ °C, unless otherwise noted)

| PARAMETER  | SYMBOL         | LIMIT                 | UNIT |
|--|----------------|-----------------------|------|
| Drain-source voltage                             | $V_{DS}$       | -30                   | V    |
| Gate-source voltage                              | $V_{GS}$       | $\pm 25$              |      |
| Continuous drain current ( $T_J = 150$ °C)       | $T_C = 25$ °C  | -25.8                 | A    |
|  | $T_C = 70$ °C  | -20.7                 |      |
|  | $T_A = 25$ °C  | -17.3                 |      |
|  | $T_A = 70$ °C  | -13.9 <sup>b, c</sup> |      |
|  | $I_{DM}$       | -60                   |      |
| Pulsed drain current ( $t = 300$ $\mu$ s)        | $T_C = 25$ °C  | -5.8 <sup>b, c</sup>  | W    |
|  | $T_A = 25$ °C  | -2.6 <sup>b, c</sup>  |      |
| Continuous source-drain diode current            | $I_S$          | -40                   |      |
| Single pulse avalanche current                   | $I_{AS}$       | 80                    |      |
| Single pulse avalanche energy                    | $E_{AS}$       | -                     |      |
| Maximum power dissipation                        | $T_C = 25$ °C  | 6.9                   |      |
|  | $T_C = 70$ °C  | 4.4                   |      |
|  | $T_A = 25$ °C  | 3.1 <sup>b, c</sup>   |      |
|  | $T_A = 70$ °C  | 2 <sup>b, c</sup>     |      |
| Operating junction and storage temperature range | $T_J, T_{stg}$ | -55 to +150           | °C   |

### THERMAL RESISTANCE RATINGS

| PARAMETER                                   | SYMBOL        | TYPICAL    | MAXIMUM | UNIT |
|---|---------------|------------|---------|------|
| Maximum junction-to-ambient <sup>b, d</sup> | $t \leq 10$ s | $R_{thJA}$ | 33      | °C/W |
| Maximum junction-to-foot (drain)            | Steady state  | $R_{thJF}$ | 15      |      |

#### Notes

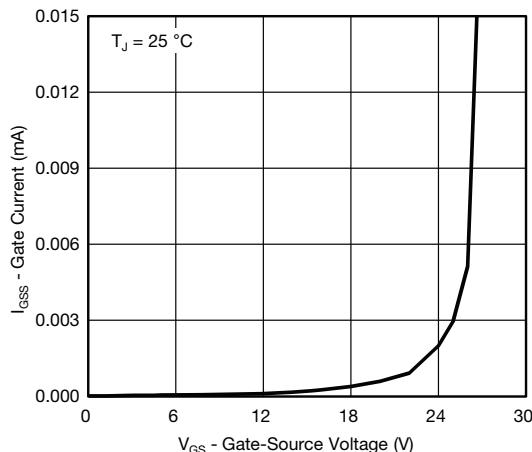
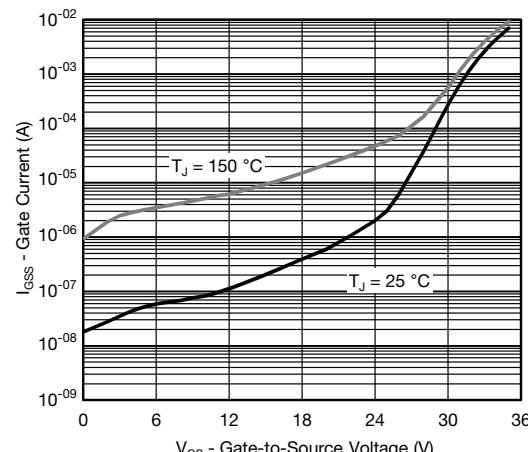
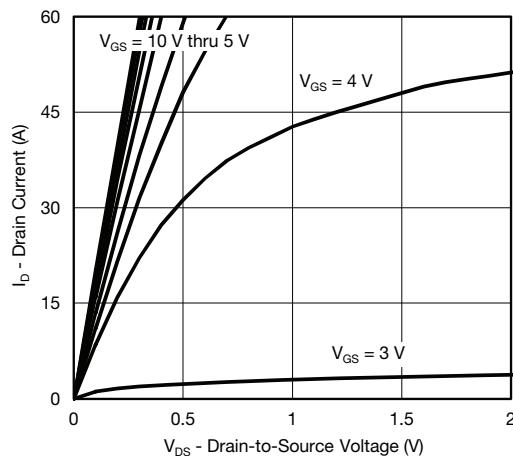
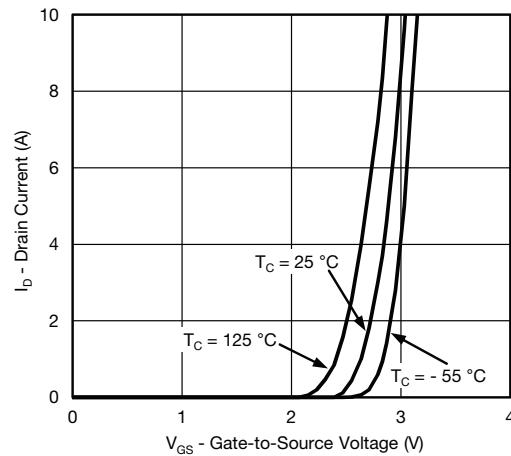
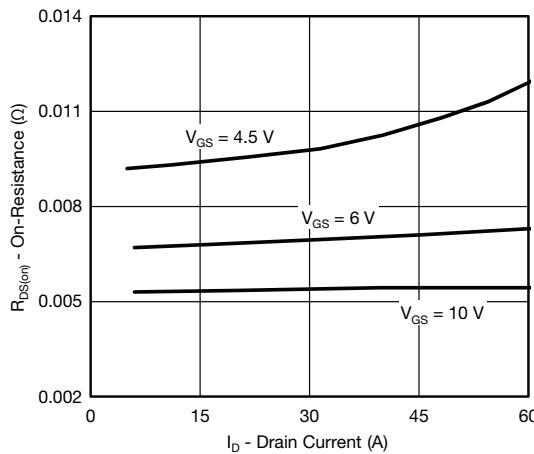
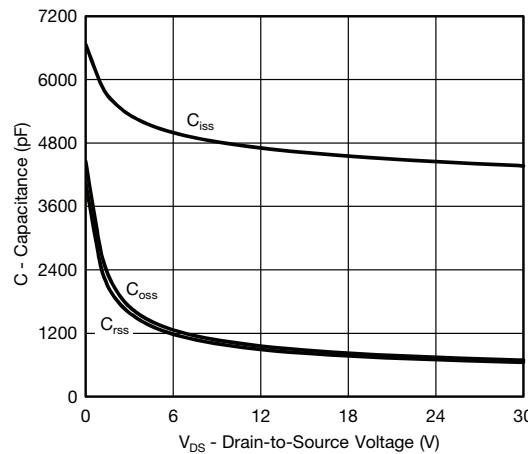
- a. Based on  $T_C = 25$  °C
- b. Surface mounted on 1" x 1" FR4 board
- c.  $t = 10$  s
- d. Maximum under steady state conditions is 90 °C/W

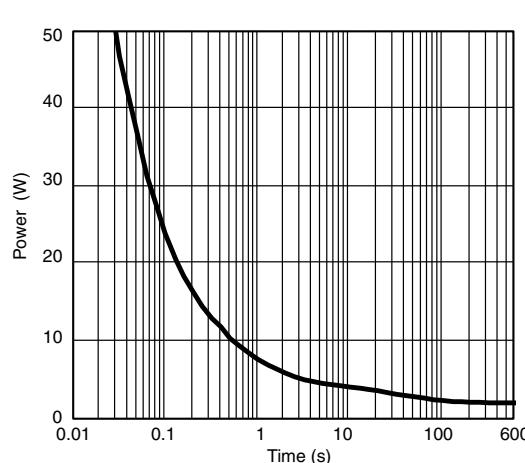
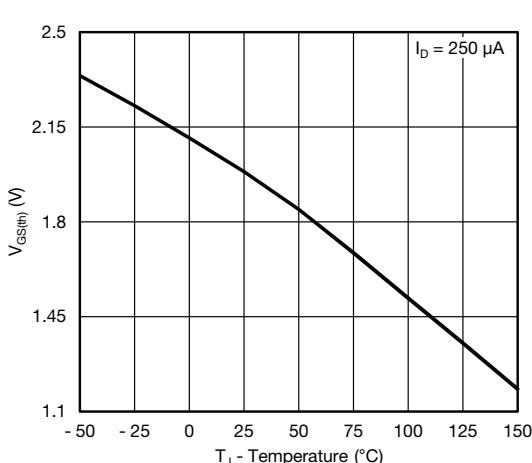
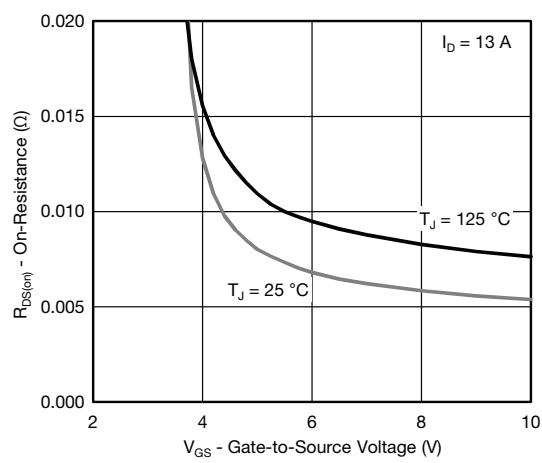
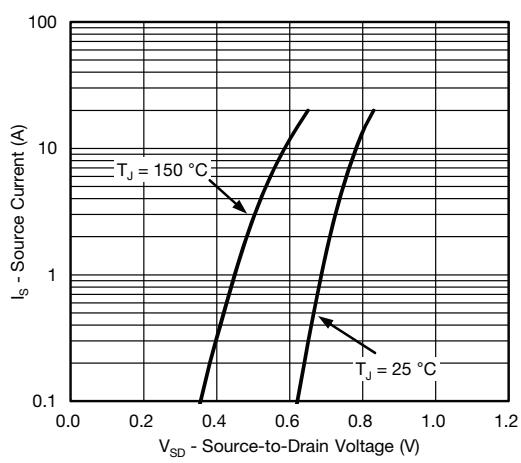
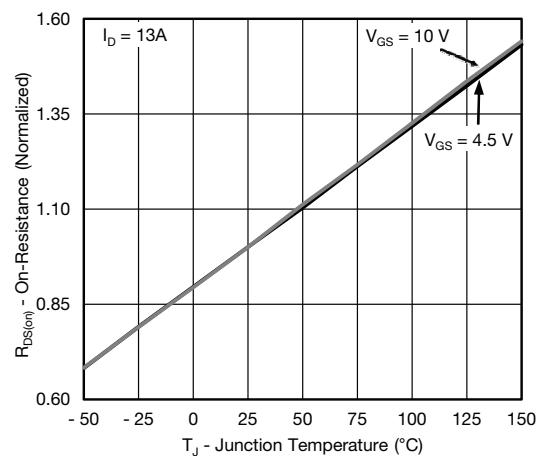
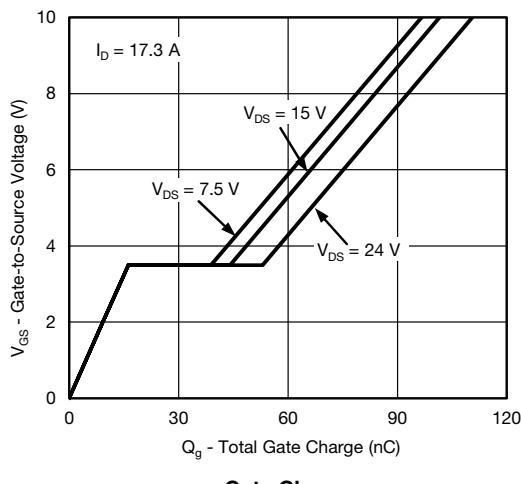
| <b>SPECIFICATIONS</b> ( $T_J = 25^\circ\text{C}$ , unless otherwise noted) |                                |  |      |        |           |       |   |
|--|--------------------------------|--|------|--------|-----------|-------|---|
| PARAMETER  | SYMBOL                         | TEST CONDITIONS  | MIN. | TYP.   | MAX.      | UNIT  |   |
| <b>Static</b>  |                                |  |      |        |           |       |   |
| Drain-source breakdown voltage   | $V_{DS}$                       | $V_{GS} = 0 \text{ V}$ , $I_D = -250 \mu\text{A}$  | -30  | -      | -         | V     |   |
| $V_{DS}$ temperature coefficient   | $\Delta V_{DS}/T_J$            | $I_D = -250 \mu\text{A}$   | -    | -24    | -         | mV/°C |   |
| $V_{GS(\text{th})}$ temperature coefficient                                | $\Delta V_{GS(\text{th})}/T_J$ |  | -    | 6      | -         |       |   |
| Gate-source threshold voltage  | $V_{GS(\text{th})}$            | $V_{DS} = V_{GS}$ , $I_D = -250 \mu\text{A}$   | -1.2 | -      | -2.8      | V     |   |
| Gate-source leakage  | $I_{GSS}$                      | $V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 25 \text{ V}$   | -    | -      | $\pm 150$ | μA    |   |
|  |                                | $V_{DS} = 0 \text{ V}$ , $V_{GS} = \pm 20 \text{ V}$   | -    | -      | $\pm 15$  |       |   |
| Zero gate voltage drain current  | $I_{DSS}$                      | $V_{DS} = -30 \text{ V}$ , $V_{GS} = 0 \text{ V}$  | -    | -      | -1        |       |   |
|  |                                | $V_{DS} = -30 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $T_J = 55^\circ\text{C}$   | -    | -      | -10       |       |   |
| On-state drain current <sup>a</sup>  | $I_{D(\text{on})}$             | $V_{DS} \leq -5 \text{ V}$ , $V_{GS} = -10 \text{ V}$  | -20  | -      | -         | A     |   |
| Drain-source on-state resistance <sup>a</sup>                              | $R_{DS(\text{on})}$            | $V_{GS} = -10 \text{ V}$ , $I_D = -13 \text{ A}$   | -    | 0.0054 | 0.0065    | Ω     |   |
|  |                                | $V_{GS} = -6 \text{ V}$ , $I_D = -10 \text{ A}$  | -    | 0.0068 | 0.0082    |       |   |
|  |                                | $V_{GS} = -4.5 \text{ V}$ , $I_D = -8 \text{ A}$   | -    | 0.0093 | 0.0112    |       |   |
| Forward transconductance <sup>a</sup>                                      | $g_{fs}$                       | $V_{DS} = -15 \text{ V}$ , $I_D = -13 \text{ A}$   | -    | 44     | -         | S     |   |
| <b>Dynamic</b> <sup>b</sup>  |                                |  |      |        |           |       |   |
| Input capacitance  | $C_{iss}$                      | $V_{DS} = -15 \text{ V}$ , $V_{GS} = 0 \text{ V}$ , $f = 1 \text{ MHz}$  | -    | 4620   | -         | pF    |   |
| Output capacitance   | $C_{oss}$                      |  | -    | 880    | -         |       |   |
| Reverse transfer capacitance   | $C_{rss}$                      |  | -    | 820    | -         |       |   |
| Total gate charge  | $Q_g$                          | $V_{DS} = -15 \text{ V}$ , $V_{GS} = -10 \text{ V}$ , $I_D = -17.3 \text{ A}$  | -    | 102    | 153       | nC    |   |
|  |                                |  | -    | 66     | 80        |       |   |
| Gate-source charge   | $Q_{gs}$                       | $V_{DS} = -15 \text{ V}$ , $V_{GS} = -5 \text{ V}$ , $I_D = -17.3 \text{ A}$   | -    | 16     | -         |       |   |
| Gate-drain charge  | $Q_{gd}$                       |  | -    | 28     | -         |       |   |
| Gate resistance  | $R_g$                          | $f = 1 \text{ MHz}$  |      | 0.3    | 1.3       | 2.6   | Ω |
| Turn-on delay time   | $t_{d(\text{on})}$             | $V_{DD} = 0 \text{ V}$ , $R_L = 1.5 \Omega$ ,<br>$I_D \approx -10 \text{ A}$ , $V_{GEN} = -4.5 \text{ V}$ , $R_g = 1 \Omega$ | -    | 70     | 105       | ns    |   |
| Rise time  | $t_r$                          |  | -    | 70     | 105       |       |   |
| Turn-off delay time  | $t_{d(\text{off})}$            |  | -    | 45     | 68        |       |   |
| Fall time  | $t_f$                          |  | -    | 27     | 41        |       |   |
| Turn-on delay time   | $t_{d(\text{on})}$             |  | -    | 18     | 30        |       |   |
| Rise time  | $t_r$                          |  | -    | 15     | 25        |       |   |
| Turn-off delay time  | $t_{d(\text{off})}$            |  | -    | 52     | 80        |       |   |
| Fall time  | $t_f$                          |  | -    | 14     | 25        |       |   |
| <b>Drain-Source Body Diode Characteristics</b>                             |                                |  |      |        |           |       |   |
| Continuous source-drain diode current                                      | $I_S$                          | $T_C = 25^\circ\text{C}$   |      | -      | -         | -5.8  | A |
| Pulse diode forward current  | $I_{SM}$                       |  |      | -      | -         | -60   |   |
| Body diode Voltage   | $V_{SD}$                       | $I_S = -10 \text{ A}$ , $V_{GS} = 0 \text{ V}$   | -    | -0.78  | -1.2      | V     |   |
| Body diode reverse recovery time   | $t_{rr}$                       | $I_F = -10 \text{ A}$ , $di/dt = 100 \text{ A}/\mu\text{s}$ ,<br>$T_J = 25^\circ\text{C}$                                    | -    | 35     | 53        | ns    |   |
| Body diode reverse recovery charge   | $Q_{rr}$                       |  | -    | 25     | 38        | nC    |   |
| Reverse recovery fall time   | $t_a$                          |  | -    | 19     | -         | ns    |   |
| Reverse recovery rise time   | $t_b$                          |  | -    | 16     | -         |       |   |

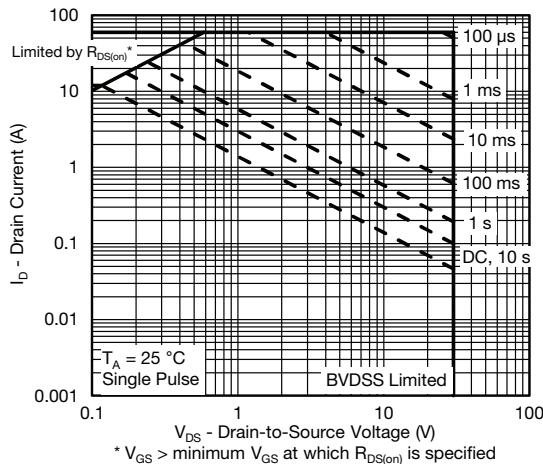
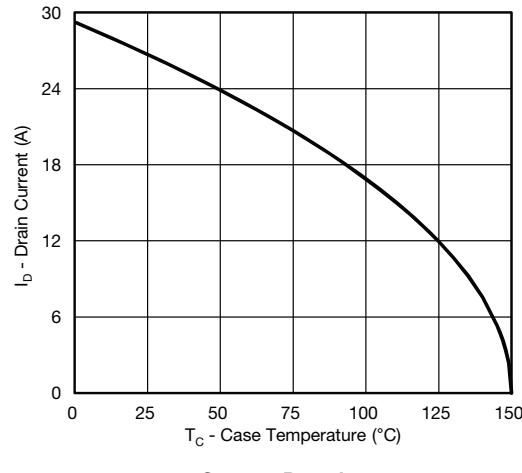
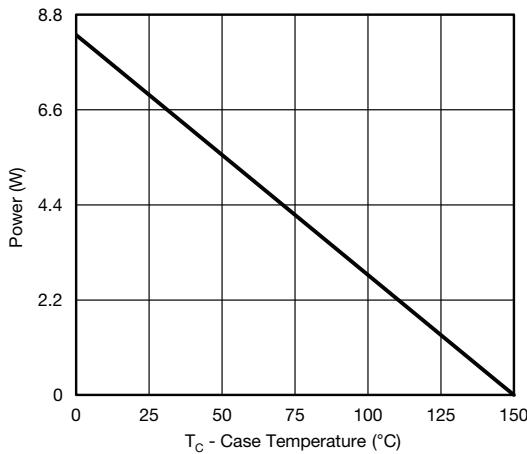
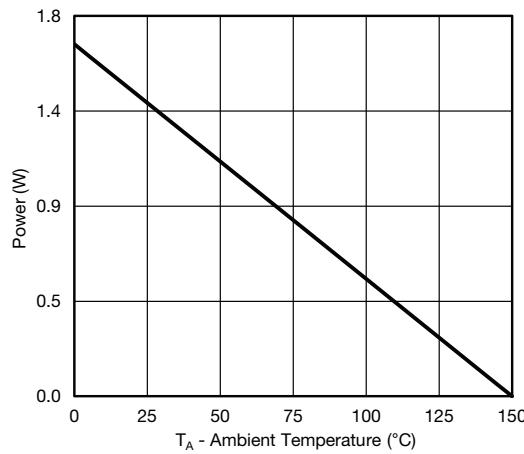
**Notes**

a. Pulse test; pulse width  $\leq 300 \mu\text{s}$ , duty cycle  $\leq 2\%$   
b. Guaranteed by design, not subject to production testing

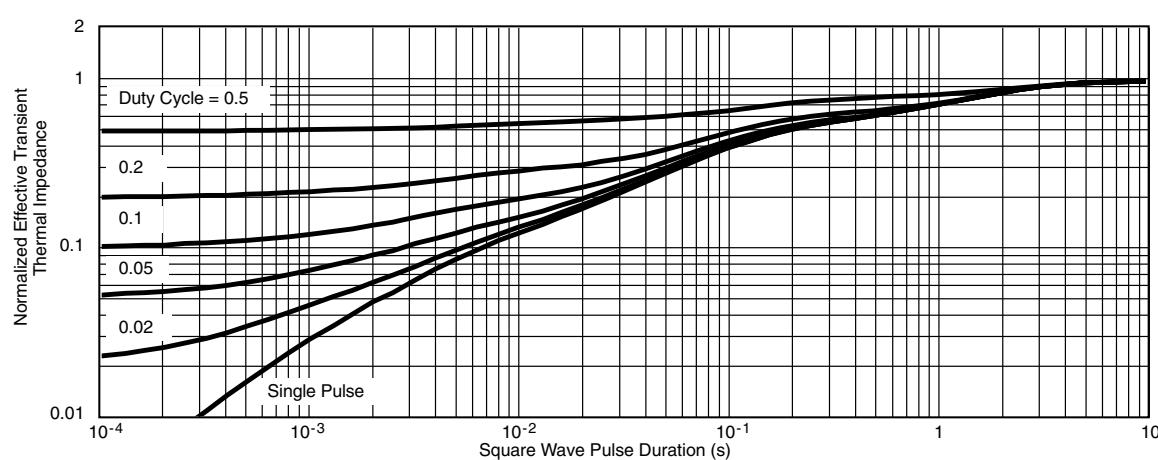
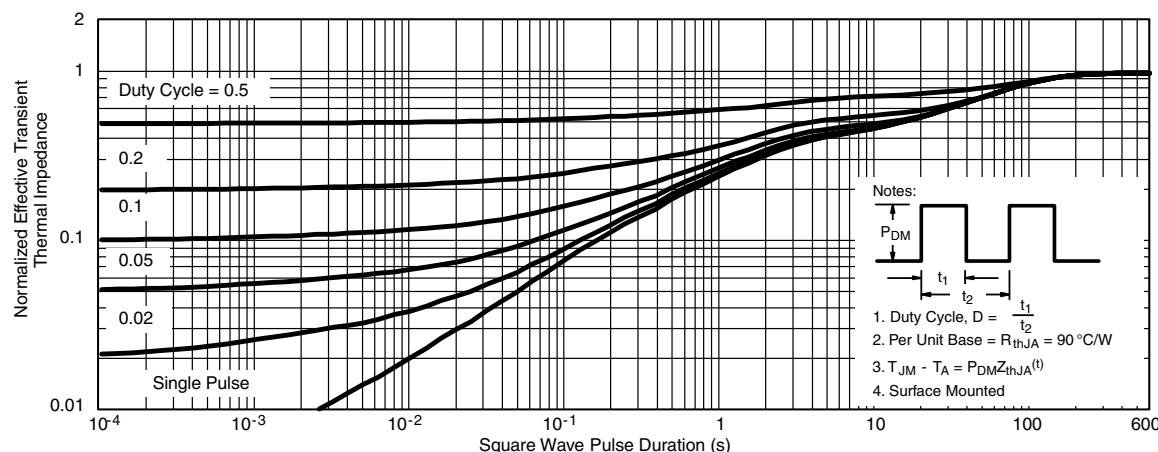
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Gate Current vs. Gate-Source Voltage**

**Gate Current vs. Gate-Source Voltage**

**Output Characteristics**

**Transfer Characteristics**

**On-Resistance vs. Drain Current**

**Capacitance**

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)


**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)

**Safe Operating Area, Junction-to-Ambient**

**Current Derating <sup>a</sup>**

**Power Junction-to-Foot**

**Power Junction-to-Ambient**
**Note**

a. The power dissipation  $P_D$  is based on  $T_J$  max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)


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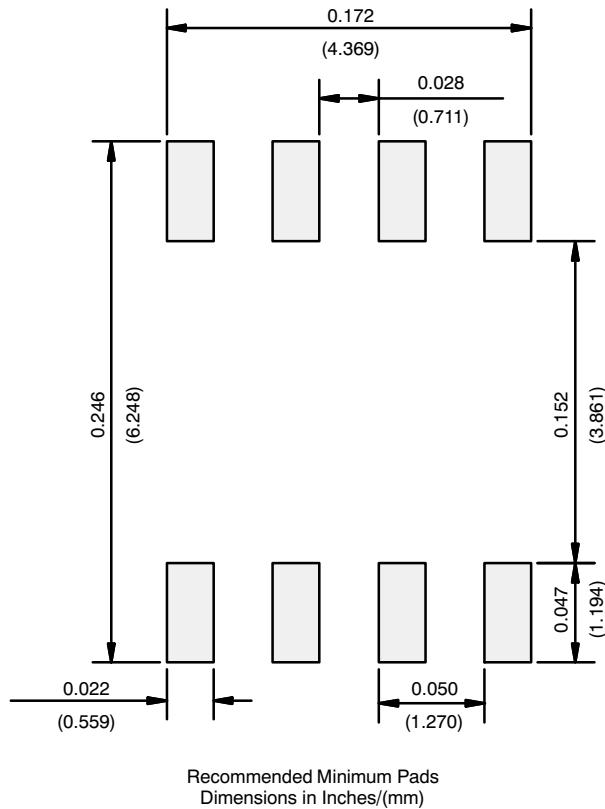
### SOIC (NARROW): 8-LEAD

JEDEC Part Number: MS-012



| DIM                            | MILLIMETERS |      | INCHES    |       |
|--------------------------------|-------------|------|-----------|-------|
|                                | Min         | Max  | Min       | Max   |
| A                              | 1.35        | 1.75 | 0.053     | 0.069 |
| A <sub>1</sub>                 | 0.10        | 0.20 | 0.004     | 0.008 |
| B                              | 0.35        | 0.51 | 0.014     | 0.020 |
| C                              | 0.19        | 0.25 | 0.0075    | 0.010 |
| D                              | 4.80        | 5.00 | 0.189     | 0.196 |
| E                              | 3.80        | 4.00 | 0.150     | 0.157 |
| e                              | 1.27 BSC    |      | 0.050 BSC |       |
| H                              | 5.80        | 6.20 | 0.228     | 0.244 |
| h                              | 0.25        | 0.50 | 0.010     | 0.020 |
| L                              | 0.50        | 0.93 | 0.020     | 0.037 |
| q                              | 0°          | 8°   | 0°        | 8°    |
| S                              | 0.44        | 0.64 | 0.018     | 0.026 |
| ECN: C-06527-Rev. I, 11-Sep-06 |             |      |           |       |
| DWG: 5498                      |             |      |           |       |

## RECOMMENDED MINIMUM PADS FOR SO-8



[Return to Index](#)

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